



SOT2150-1

FCD2, flip chip die, 2 terminals, 0.51 mm pitch, 0.808 mm x 0.528 mm x 0.408 mm body

29 July 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FCD2
Package style descriptive code	FCD (flip chip die)
Mounting method type	S (surface mount)
Issue date	18-06-2021
Manufacturer package code	98ASA01808D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.525	0.528	0.531	mm
package width	0.805	0.808	0.811	mm
package height	-	0.408	0.435	mm
nominal pitch	-	0.51	-	mm
actual quantity of termination	-	2	-	



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2 Package outline

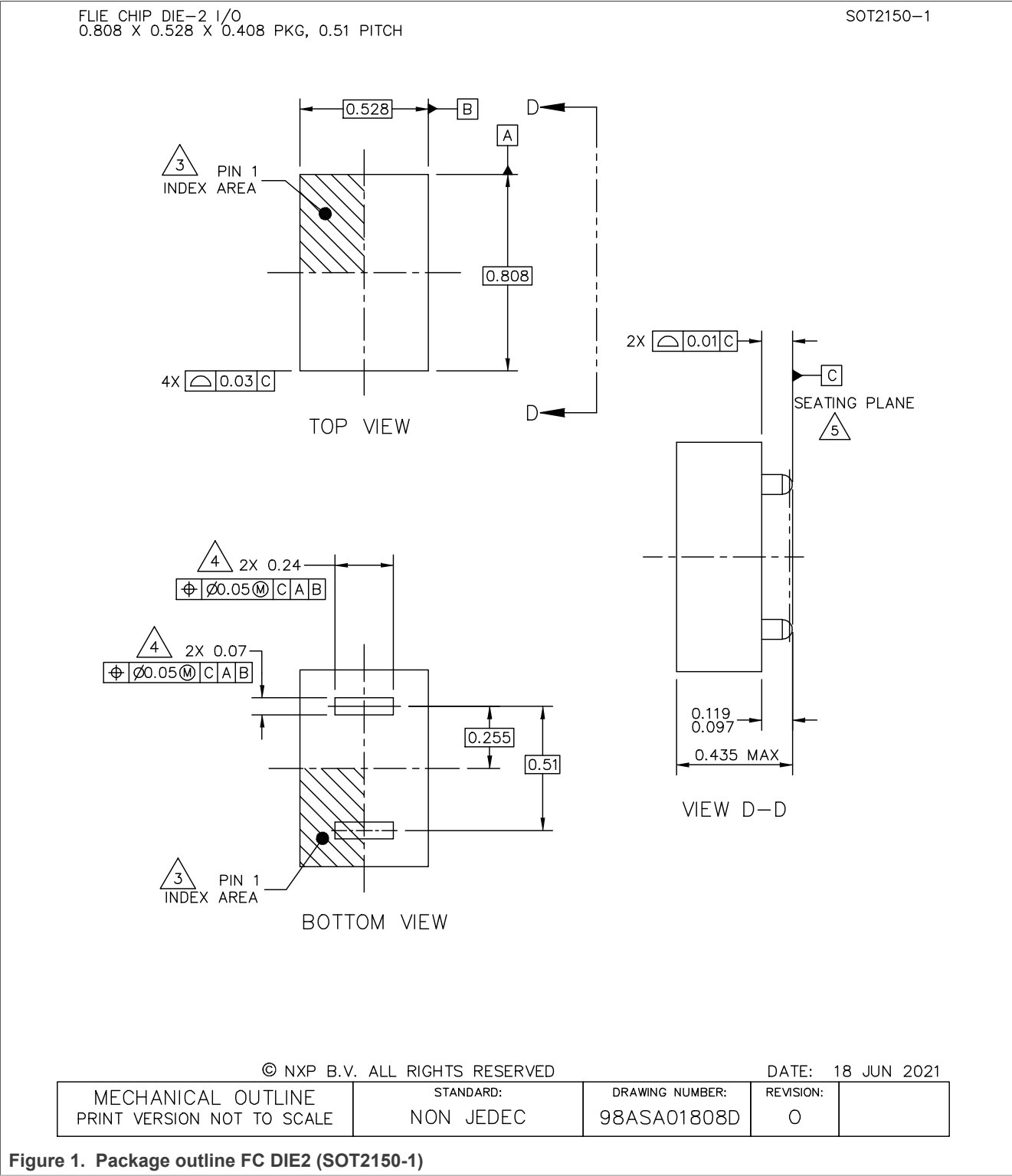


Figure 1. Package outline FC DIE2 (SOT2150-1)

FCD2, flip chip die, 2 terminals, 0.51 mm pitch, 0.808 mm x 0.528 mm x 0.408 mm body

FLIE CHIP DIE-2 I/O
0.808 X 0.528 X 0.408 PKG, 0.51 PITCH

SOT2150-1

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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DATE: 18 JUN 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01808D	REVISION: 0	
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Figure 2. Package outline note FC DIE2 (SOT2150-1)

3 Legal information

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